

# NTSC → PAL Converter Monolithic IC MM1130

## Outline

This is an NTSC/PAL signal switching IC.

In PAL conversion mode, a frequency-converted ( $f_c=4.43\text{MHz}$ ) NTSC format chroma signal is phase converted (R-Y axis component is inverted) every 1 hour by shifting burst signal phase by  $45^\circ$ .

Circuit configuration includes VCO (horizontal sync), VCXO (phase conversion carrier), phase conversion circuit, switches, amps, etc.

## Features

1. PAL conversion with phase conversion performed
2. Two possible phase conversion carriers : crystal oscillation and external input
3. No adjustments
4. Four possible mode selections by CTL and EXT pins

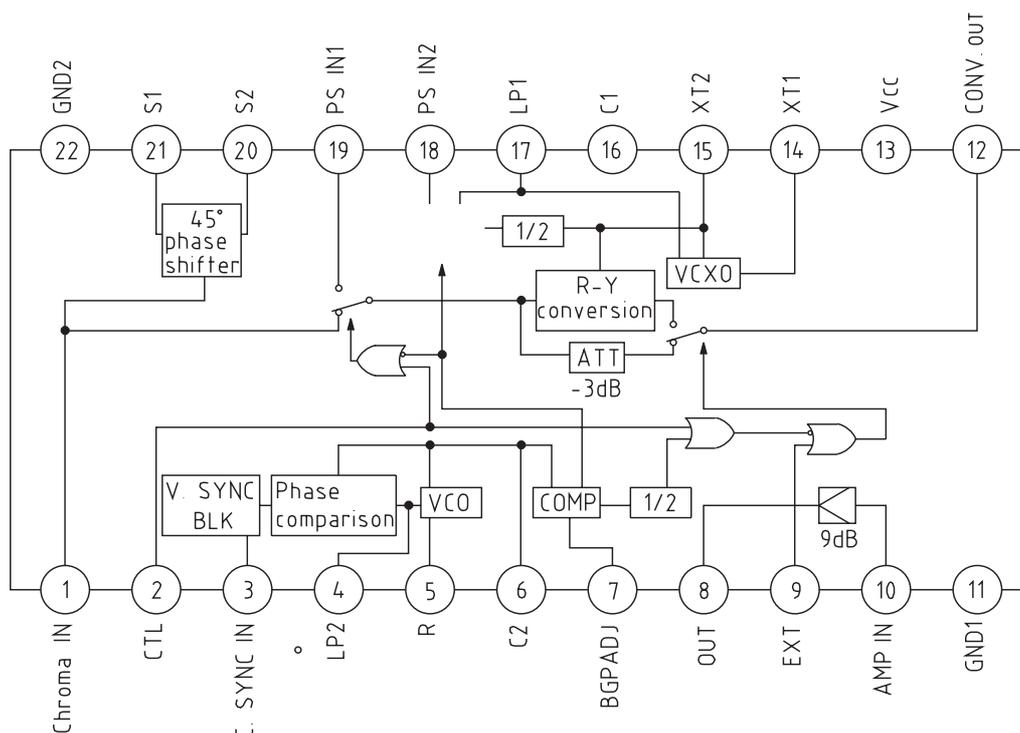
## Package

SDIP-22A (MM1130XD)

## Applications

1. VCR

## Block Diagram



Pin Description

Pin no.	Pin name	Function	Internal equivalent circuit diagram
1	chroma IN	Inputs chroma signal	
2	CTL	Mode setting pin	
3	C.SYNC IN	Inputs composite sync signal	
4	LP2	Time constant connection pin for H. SYNC APC loop LPF	
5	R	H. SYNC APC feedback pin	
6	C2	Pin for connecting H. SYNC APC free run frequency setting capacitor	
7	BGP ADJ	Fine tuning of position for sampling burst signal. Use open.	

Pin no.	Pin name	Function	Internal equivalent circuit diagram
8	OUT	Amp output pin	
9	EXT	Mode setting pin	
10	AMP IN	Amp input pin	
11	GND1	GND pin	
12	CONV.out	Multiplication circuit output pin	
13	Vcc	Vcc pin. Inputs 5V.	
14	XT1	Carrier (2fsc) oscillation circuit output pin	
15	XT2	Carrier (2fsc) input pin	

Pin no.	Pin name	Function	Internal equivalent circuit diagram
16	C1	Carrier APC phase shift pin	
17	LP1	Time constant connection pin for carrier APC loop LPF	
18	PS IN2	Carrier APC input pin. Pin 18 input signal burst signal and carrier signal are phase locked.a	
19	PS IN1	Burst signal phase input pin during PAL conversion.	
20	S2	Phase shift circuit output pin. Signal is Pin 21 output inverted.	
21	S1	Phase shift circuit output pin. Signal is Pin 20 output inverted.	
22	GND2	GND pin	

**Absolute Maximum Ratings** (Ta=25°C)

Item	Symbol	Ratings	Units
Storage temperature	T <sub>STG</sub>	-40~+125	°C
Operating temperature	T <sub>OPR</sub>	-20~+75	°C
Power supply voltage	V <sub>CC</sub> max.	7	V
Allowable loss	P <sub>d</sub>	600	mW

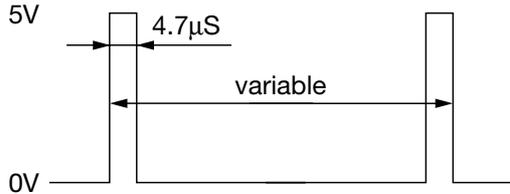
**Electrical Characteristics** (Except where noted otherwise, Ta=25°C, V<sub>CC</sub>=5.0V, SW13 : b)

Item	Symbol	Measurement circuit	Measurement conditions	Min.	Typ.	Max.	Units
Operating power supply voltage	V <sub>CC</sub>			4.7	5.0	5.3	V
Consumption current	I <sub>CC</sub>	13	SW2, 9, 13 : a, no input		29.0	40.0	mA
Dynamic range	D			0.8			V <sub>P-P</sub>
<b>Slew mode (SW2 : b, SW9 : a, V<sub>IN1</sub>=SG1, V<sub>IN3</sub>=SG2)</b>							
Gain	G <sub>t</sub>	8	*1	-1.0	0	1.0	dB
Phase difference	∠θ <sub>t</sub>	8	*2	-5	0	5	deg
<b>PAL conversion mode Hn (SW2 : a, SW9 : a, V<sub>IN1</sub>=SG1, V<sub>IN3</sub>=SG2) *3</b>							
Burst gain	G1 <sub>bt</sub>	8	*1	-1.0	0	1.0	dB
Red gain	G1 <sub>r</sub>	8	*1	-1.0	0	1.0	dB
Green gain	G1 <sub>g</sub>	8	*1	-1.0	0	1.0	dB
Blue gain	G1 <sub>b</sub>	8	*1	-1.0	0	1.0	dB
Burst phase	θ1 <sub>bt</sub>	8		130.0	135.0	140.0	deg
Red phase	θ1 <sub>r</sub>	8		98.5	103.5	108.5	deg
Green phase	θ1 <sub>g</sub>	8		235.6	240.6	245.6	deg
Blue phase	θ1 <sub>b</sub>	8		342.6	347.6	352.6	deg
<b>PAL conversion mode Hn+1 (SW2 : a, SW9 : a, V<sub>IN1</sub>=SG1, V<sub>IN3</sub>=SG2) *3</b>							
Burst gain	G2 <sub>bt</sub>	8	*1	-1.0	0	1.0	dB
Red gain	G2 <sub>r</sub>	8	*1	-1.0	0	1.0	dB
Green gain	G2 <sub>g</sub>	8	*1	-1.0	0	1.0	dB
Blue gain	G2 <sub>b</sub>	8	*1	-1.0	0	1.0	dB
Burst phase	θ2 <sub>bt</sub>	8		-145.0	-135.0	-125.0	deg
Red phase	θ2 <sub>r</sub>	8		-113.5	-103.5	-93.5	deg
Green phase	θ2 <sub>g</sub>	8		-250.6	-240.6	-230.6	deg
Blue phase	θ2 <sub>b</sub>	8		-357.6	-347.6	-337.6	deg
<b>(SW2 : a, SW9 : a, V<sub>IN1</sub>=SG1, V<sub>IN3</sub>=SG2)</b>							
DC step	∠V	8	*4			40	mV
BGP timing	t <sub>1</sub>	8	*5	3.5	4.3	5.1	μS
BGP width	t <sub>2</sub>	8	*5	3.7	4.5	5.3	μS
Hn/Hn+1 switching timing	t <sub>3</sub>	8	*5	-0.6	0.2	1.0	μS
<b>VCO (SW2 : a, SW9 : a, V<sub>IN1</sub> : N0)</b>							
Free-running frequency	f <sub>o1</sub>	6	V <sub>IN3</sub> : GND	14.2	15.7	17.2	kHz
Acquisition range	f <sub>c1</sub>	6	V <sub>IN3</sub> : SG3 *6	1.5			kHz
<b>VCXO (SW2 : b, SW9 : b)</b>							
Free-running frequency	f <sub>o2</sub>	14	V <sub>IN1</sub> : No, V <sub>IN3</sub> : 5.0V	8.86 6438	8.86 7238	8.86 8038	MHz
Acquisition range	f <sub>c2</sub>	14	V <sub>IN1</sub> : SG4, V <sub>IN3</sub> : SG2 *7	400			Hz
<b>(SW2 : b, SW9 : b, V<sub>IN1</sub>=SG5, V<sub>IN3</sub>=SG3)</b>							
Carrier leak	V <sub>c1</sub>	12	*8			-20	dB
<b>Control pin input resistance (V<sub>IN1</sub>=SG1, V<sub>IN3</sub>=SG2)</b>							
CTL pin switching voltage	V <sub>t1</sub>	3	Lower pin 3 from 5V. Voltage when pin 8 switches.	0.7	1.4	2.1	V
EXT pin switching voltage	V <sub>t2</sub>	9	Lower pin 9 from 5V. Voltage when pin 8 switches.	0.7	1.4	2.1	V

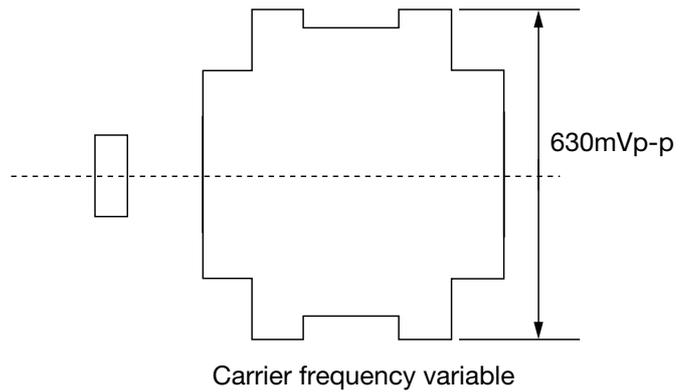
Input Signals

SG1	Color bar chroma signal $f=4.433619\text{MHz}$ $V=630\text{mV}_{P-P}$
SG2	C. SYNC signal $0V-5V$
SG3	15.74kHz pulse wave $f$ : frequency variation $0V-5V$
SG4	Color bar chroma signal $f$ : frequency variation $V=630\text{mV}_{P-P}$
SG5	Continuous sine wave $f$ : $4.433619\text{MHz}$ $V=630\text{mV}_{P-P}$

SG3

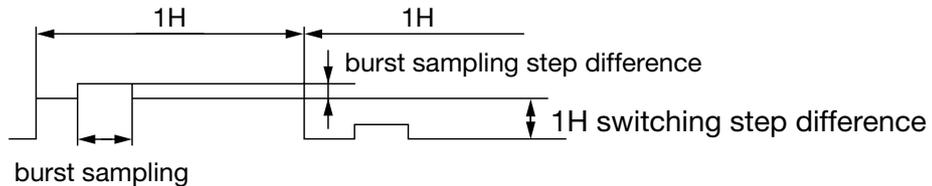


SG4

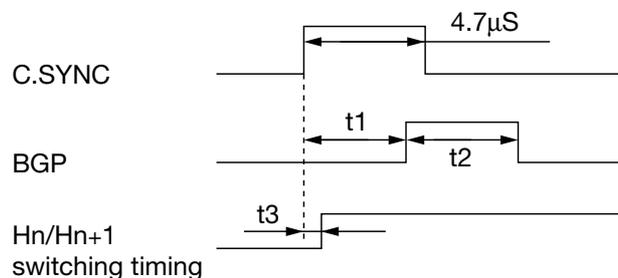


Notes:

- \*1 Gain is calculated by  $20\log(\text{Pin 8 level}/\text{Pin 1 level})$ .
- \*2 Phase difference is difference between input and output phases (given B-Y axis as  $0^\circ$ .)
- \*3  $H_n$  output is 1 horizontal output after input signal burst is shifted  $+45^\circ$ .  $H_{n+1}$  output is 1 horizontal output after input signal burst is shifted  $+45^\circ$ , and that signal is R-Y converted.
- \*4 DC step difference is the total of burst sampling step different during PAL conversion and 1H switching step difference.



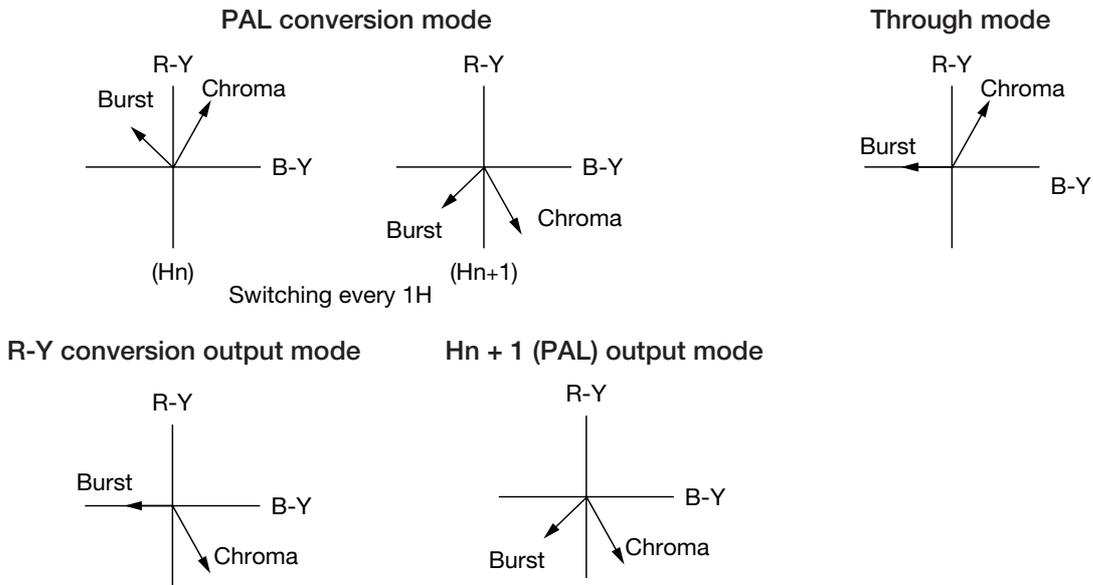
\*5 BGP,  $H_n/H_{n+1}$  Switching Timing



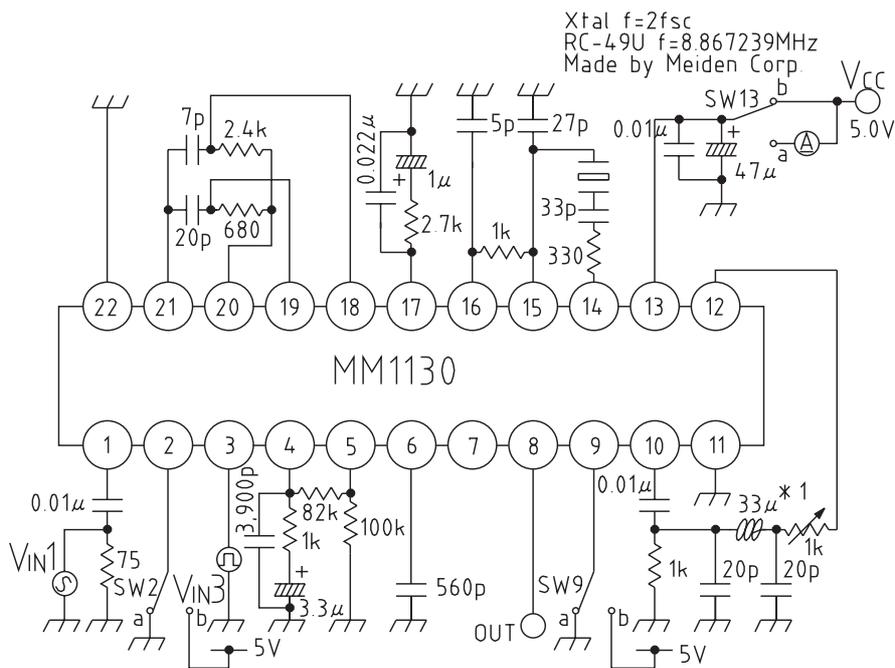
- \*6 This is the smaller of frequency  $f$  and horizontal sync signal frequency ( $f_H=15.73\text{kHz}$ ) difference when the frequencies are separated sufficiently high and low, then brought closer, and the waveform locks.
- \*7 This is the smaller of frequency  $f$  and carrier frequency ( $f_C=4.433619\text{MHz}$ ) difference when the frequencies are separated sufficiently high and low, then brought closer, and the waveform locks.
- \*8 Carrier leak is the 8.86MHz component level at Pin 12.  
 $V_{c1}=20\log(8.86\text{MHz component}/4.43\text{MHz component}) \text{ dB}$

Mode Settings

CTL	EXT	
L	L	PAL conversion mode
H	L	Through mode
H	H	R-Y conversion mode
L	H	Hn + 1 (PAL) output mode



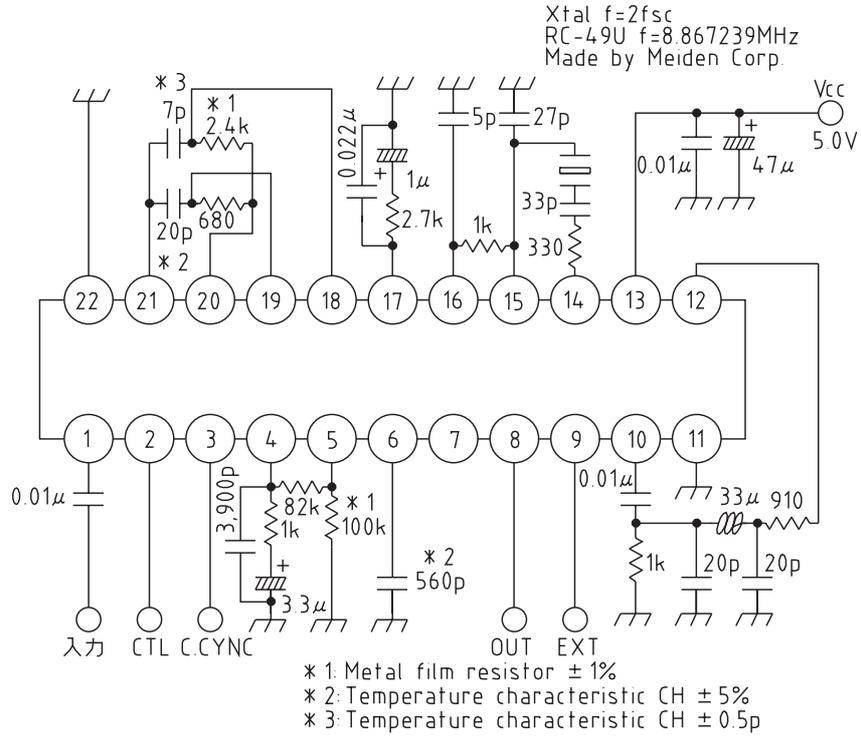
Measuring Circuit



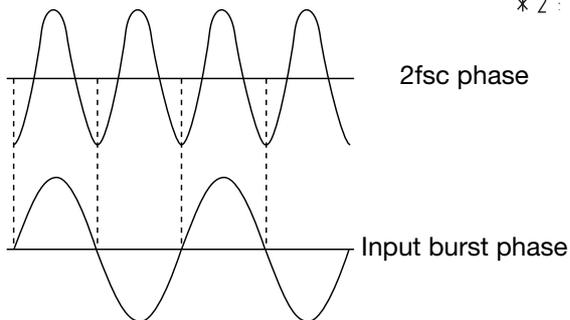
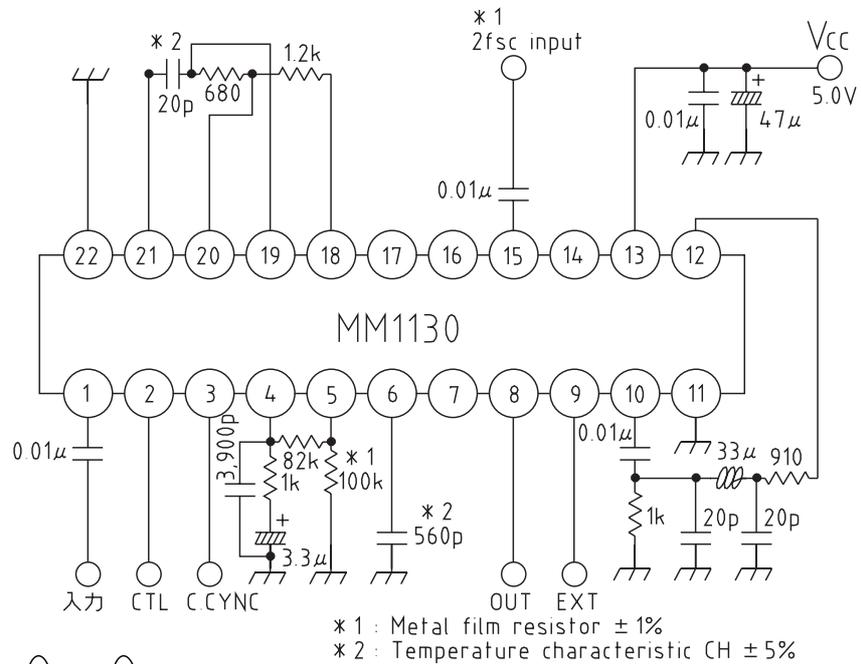
Note: \* 1 Adjust filter level characteristics so that  $f = 4.43\text{MHz}$ , level = -5.5dB with 1k $\Omega$  semifixed resistor.

Application Circuits

1. For crystal oscillation of 2fsc



2. For external input of 2fsc



\*1 Regarding 2fsc input  
Input 2fsc with input level of more than 500mV<sub>P-P</sub> and phase as shown in the figure at left.